

ABSTRACT:

An epoxy resin composition for sealing a semiconductor device, including an epoxy resin in an amount of about 0.8 to about 1.2 times the epoxy equivalents per hydroxyl group equivalent of the total phenolic resin, a phenolic resin curing hardener, an inorganic filler in an amount of about 30 to about 75% by weight of the composition, an aluminum hydroxide flame retardant in an amount of about 21 to about 45% by weight of the composition, a curing accelerator in an amount of about 0.2 to about 0.5% by weight of the composition, and a releasing agent in an amount of less than about 1.0% by weight of the composition.